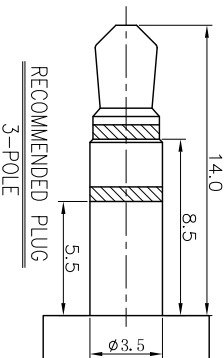
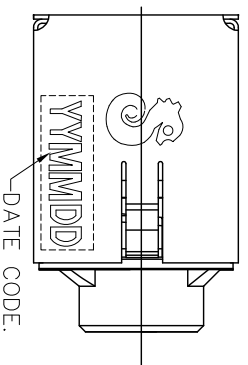
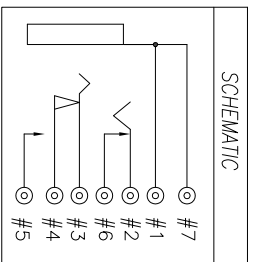


RECOMMENDED PCB LAYOUT (TOP VIEW)  
(TOLERANCE: ±0.05)



SCHEMATIC



- SPECIFICATIONS:
- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100M Ω MEASURED BY 500 VDC MEGGER.
  - CONTACT RESISTANCE: 30m Ω MAX.
  - INSULATION VOLTAGE WITHSTAND:  
500V AC FOR ONE MINUTE.
  - UNLESS OTHERWISE SPECIFIED. TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT, IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60-70% IN HUMIDITY.
  - LIFE TEST: 5,000 CYCLES MIN. (NON-LOAD)
  - INSERTION FORCE: 0.4 - 3Kg.
  - WITHDRAWAL FORCE: 0.3 - 2Kg.
  - AFTER LIFE TEST, CONTACT RESISTANCE: 50m Ω MAX.
  - AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50M Ω MIN.
  - MARKING: MARK "G.P." ON TOP OF CONNECTOR.
  - PACKAGING : TAPE & REEL.
  - TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC
  - GREEN PRODUCT IDENTIFICATION MARK ON JACK:
  - GREEN PRODUCT IDENTIFICATION LABEL ON PACKAGING: **G.P. PASS**
  - FOR LEAD-FREE PROCESS.

NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
A	BODY	1	HIGH TEMP THERMOPLASTIC UL 94V-0	RED(1807C)
B	EARTH	1	COPPER ALLOY 0.2t	Ag20u" Over Ni 50u" MIN
C	TIP SPRING	1	PHOSPHOR BRONZE 0.25t	GOLD FLASH ON CONTACT AREA OVER 50u" IN PLATING.
D	SHUNT TERMINAL-A	1	BRASS 0.25t	
E	RING SPRING	1	PHOSPHOR BRONZE 0.2t	
F	BREAK TERMINAL	1	PHOSPHOR BRONZE 0.2t	GOLD FLASH ON CONTACT AREA 120u" SN ON SOLDER TAIL AREA ALL OVER 50u" IN PLATING.
G	TRANSFER TERMINAL	1	PHOSPHOR BRONZE 0.2t	Ni 60u" PLATING MIN.
H	SHIELDING	1	PHOSPHOR BRONZE 0.2t	

DECIMALS:	ANGLES:
X. :±0.5	X :±2°
X.X :±0.3	X.X :±1°
X.XX :±0.2	
X.XXX :±0.1	

TITLE	PART NO.	UNIT	SHEET	REV.
DWN Swino	3.5φ PHONE JACK	2S1-S351-038	1	B
CHKD Lussen	SCALE:4:1	mm		
APVD Tony	SIZE: A3		1 OF 1	

CUSTOMER COPY

REV.	ECON NO	OR DESCRIPTION	REVISED	DATE
A	PDR:1091027-1A		Bruce	2009.11.12
B	ECON NO.S110320		Swino	2011.03.10